



ATLAS Pixel IBL QA

In and around SR1

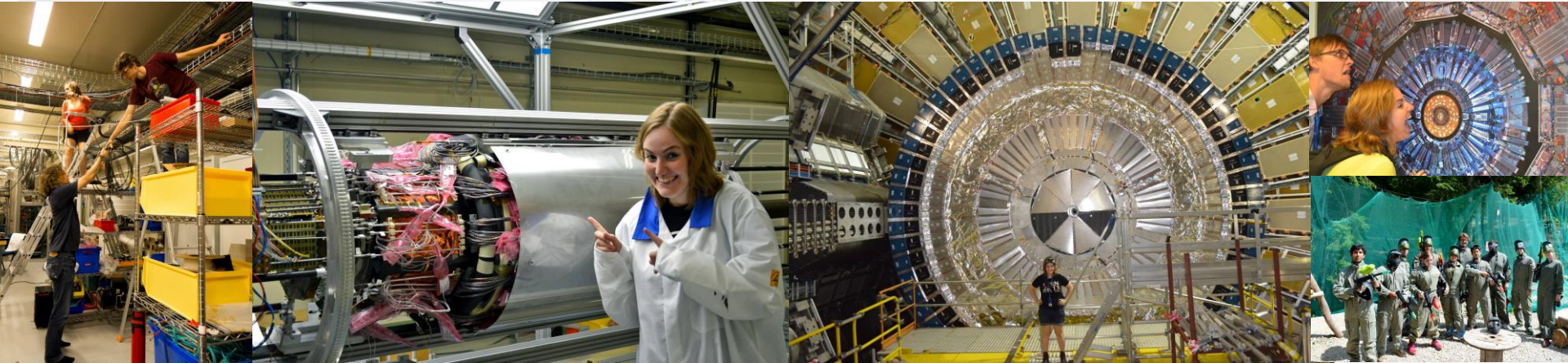
Overview

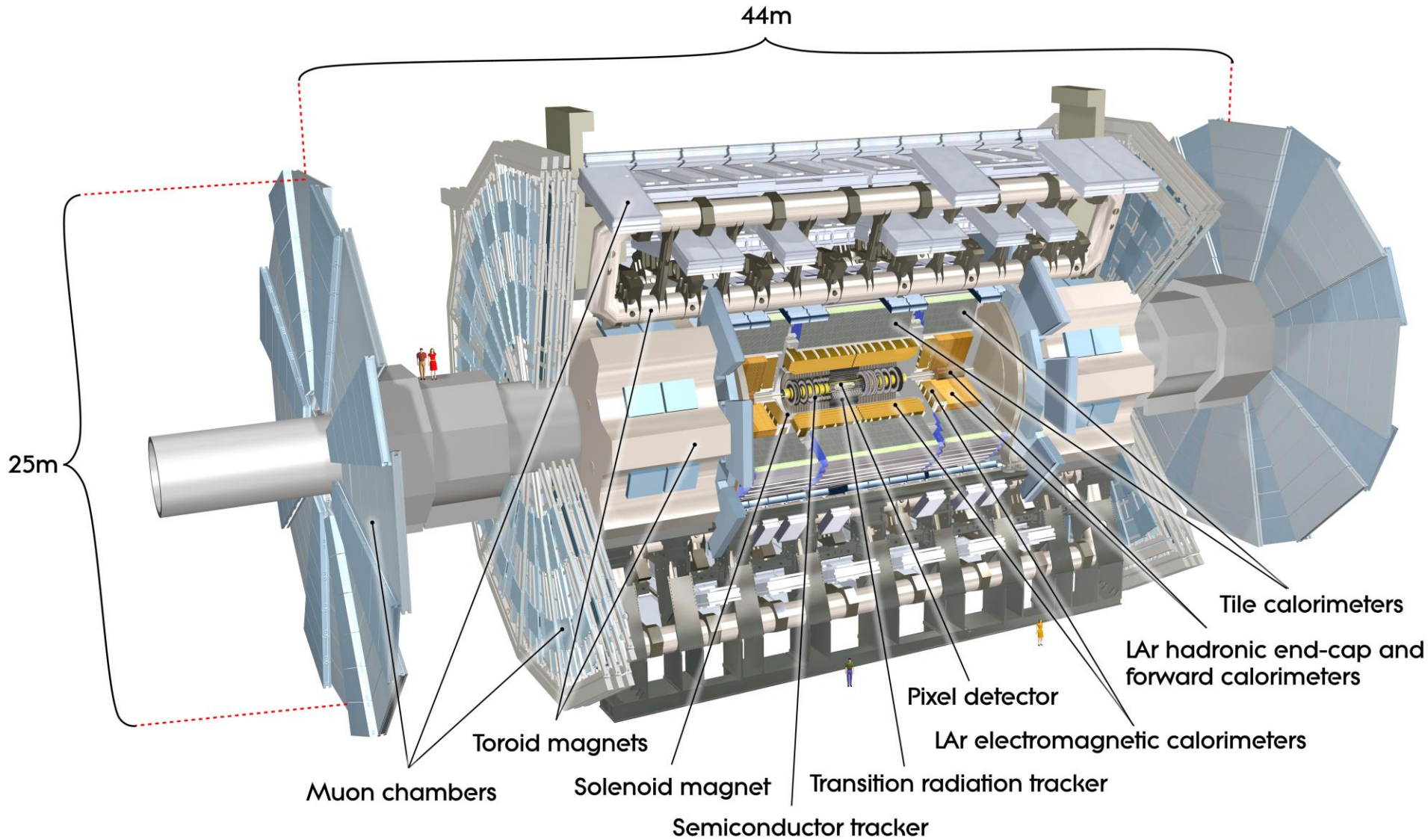
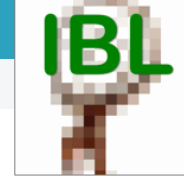
A selection from the ATLAS Pixel Upgrade – what, when, who, why, how?

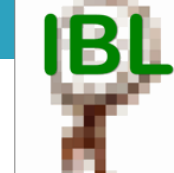
How you too can build your very own IBL!

What have I actually been doing? Part 1 – Analyse This

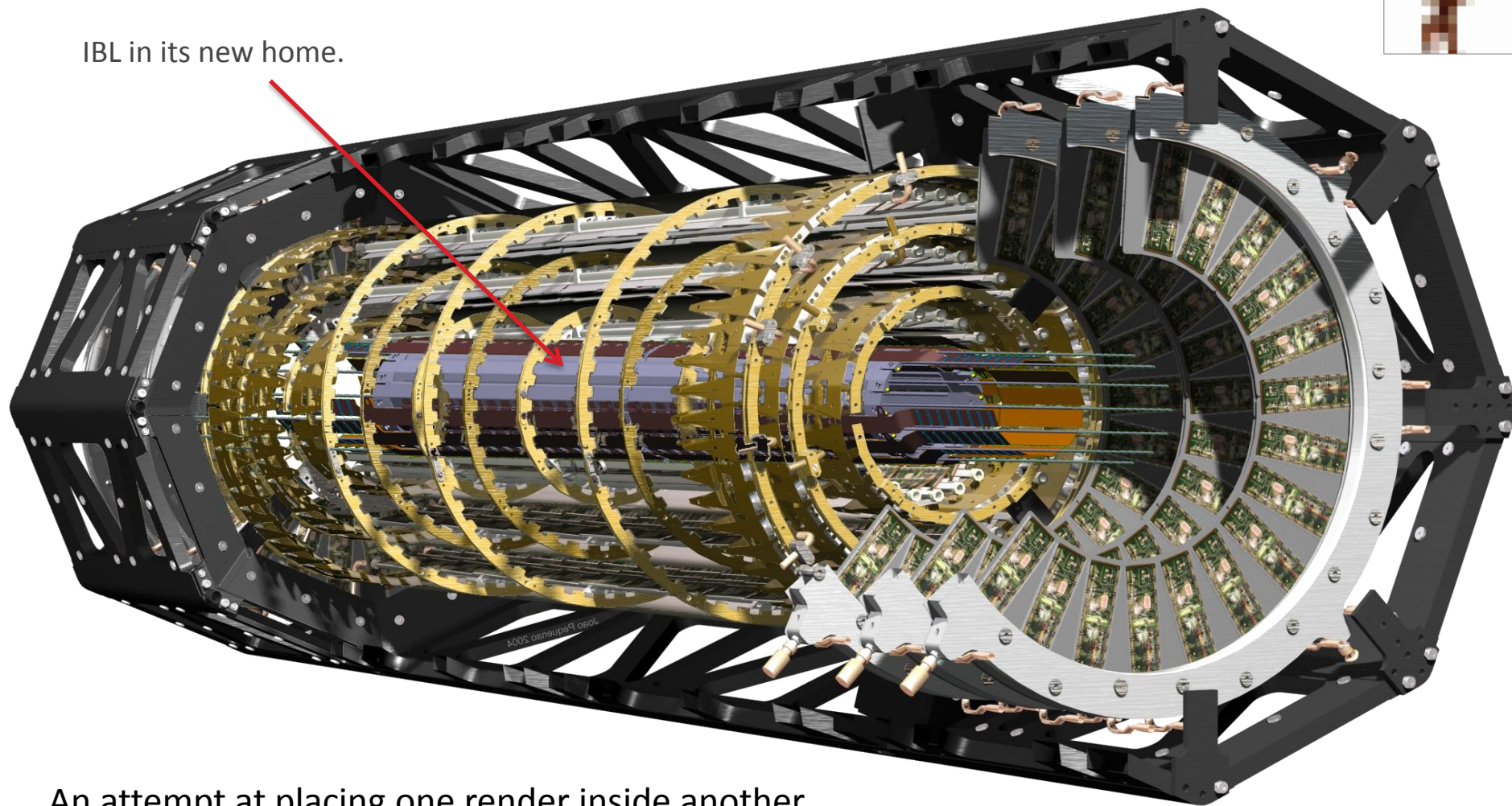
What have I actually been doing? Part 2 – A Tale of Two Noises







IBL in its new home.



An attempt at placing one render inside another.
Not shown here: services, beam pipe, IBL Support
Tube (IST), most of the existing Pixel.



ATLAS TDR 19
September 2010

CERN-LHCC-2010-013
September 2010

ATLAS
Insertable **B-Layer**
Technical Design Report

TDR

IBL



9 April 2013



The FE-I4B Integrated Circuit Guide

FE-I4 Collaboration

ABSTRACT: Detailed reference of the FE-I4 integrated circuit version B. Much of the text is the same as the FE-I4A guide, but register assignments, pads, etc. should be updated. Early versions will not have all the needed updates.

KEYWORDS: ATLAS, LHC, Upgrade, Pixel detector, Insertable B layer, CERN.

2007 – FEI4 task force

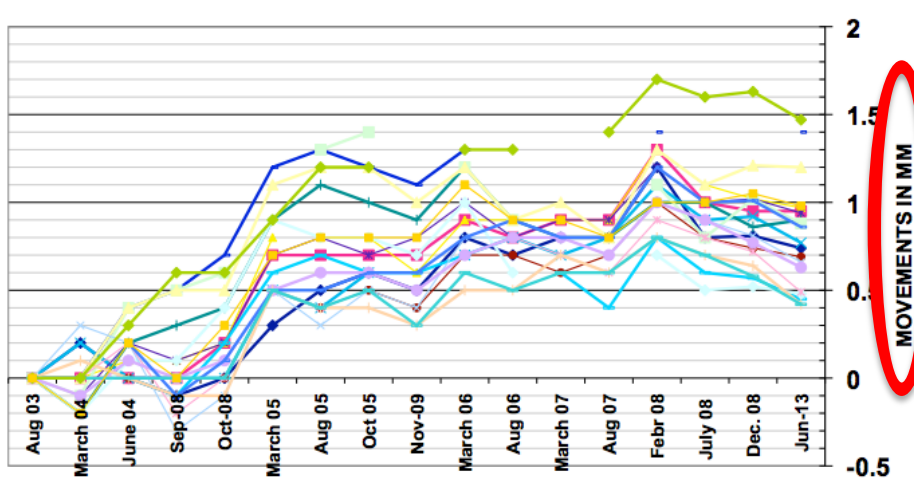


2008 – IBL task force

2010 – Technical Design Report

2013 - Construction and integration

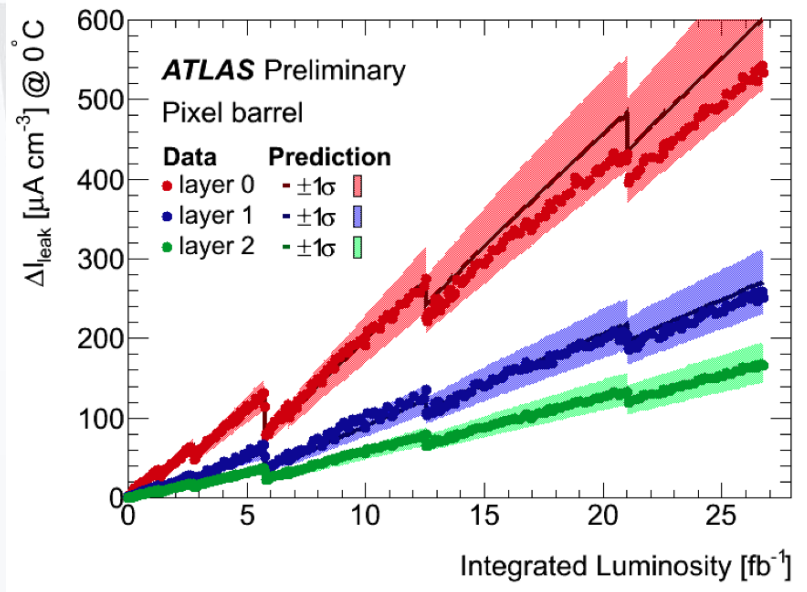
FLOOR STABILITY : CUMULATIVE MOVEMENTS AUGUST 03 - JUNE 09



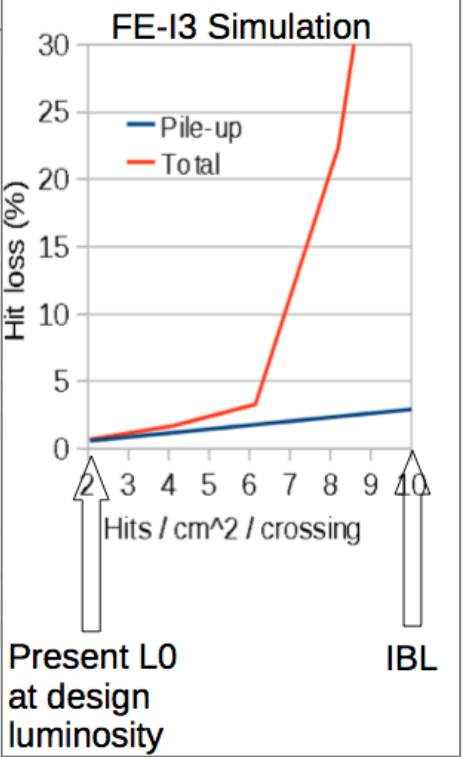
Why are we bothering?

Compensate for the loss of full coverage as the detector reaches higher luminosities.

The LHC has delivered $\sim 30\text{fb}^{-1}$ or 6×10^{13} $1\text{MeV } n_{\text{eq}}/\text{cm}^2$. Pixel will last for of the order of 10 times more radiation.

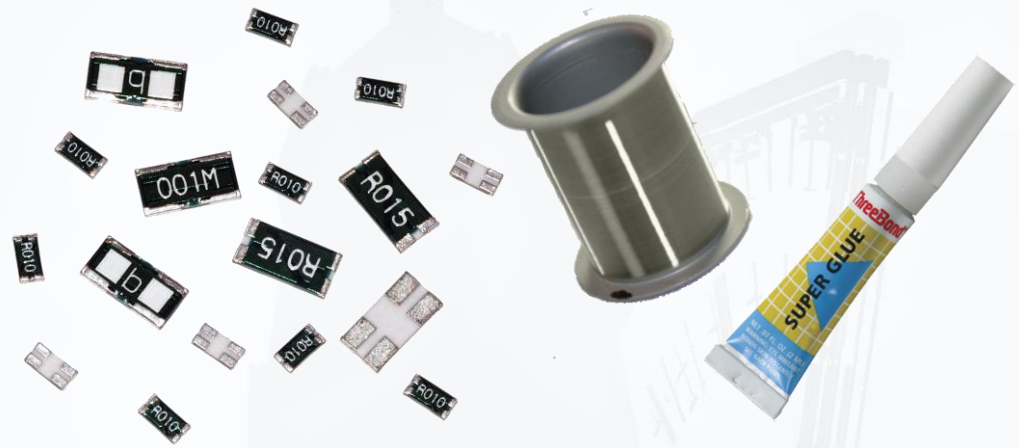
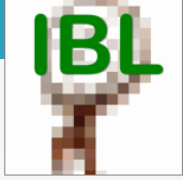


Prof. D. Bortoletto, *Detectors for Particle Physics: Semiconductor detectors, CERN Summer Student Lectures 2013*



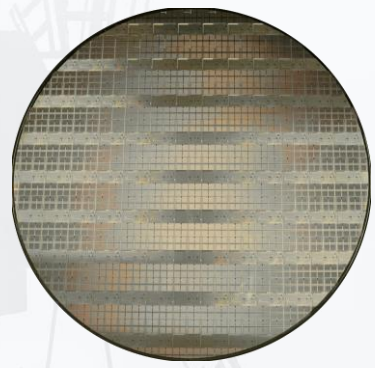
The HL-LHC (Phase-II) upgrade also requires a tracker that is more radiation hard.

IBL is a way of testing these new technologies whilst providing a higher sensitivity for B-tagging for the next data taking period.

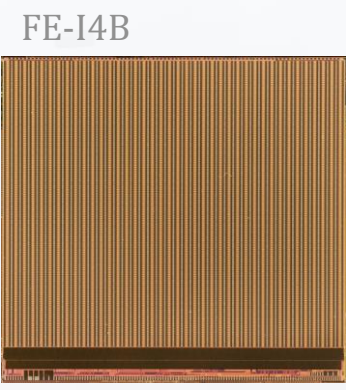


Insertable B-layer shopping list

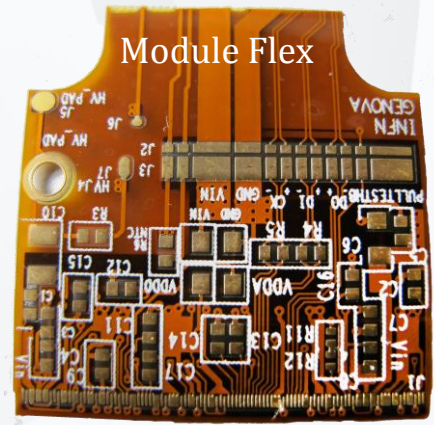
- Skilled individuals at established institutes across the world.
- Planar and 3D Silicon Sensors
- FE-I4B readout chip x 32 x 14
- Module and stave kapton flex PCB's
- Carbon foam/fibre stave
- Surface mount components
- 0.1 um aluminium thread
- Lots of glue!



Silicon sensors



FE-I4B



Module Flex



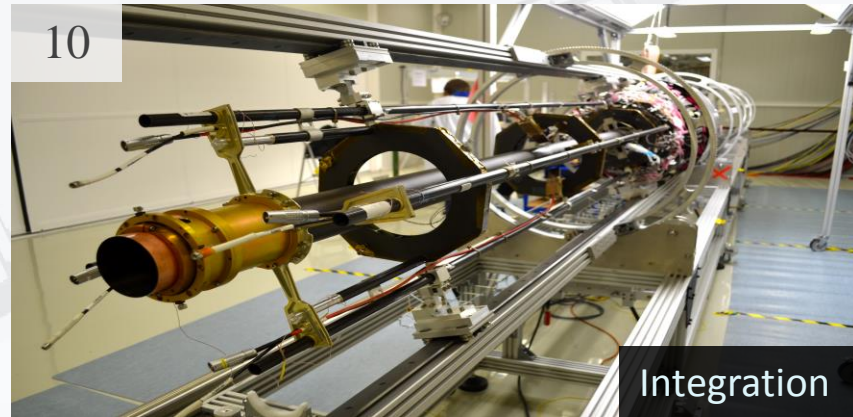
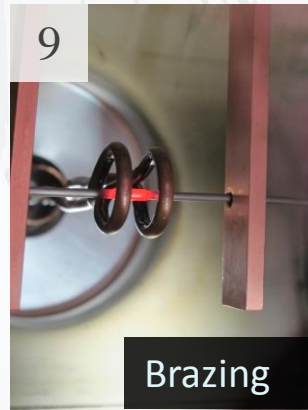
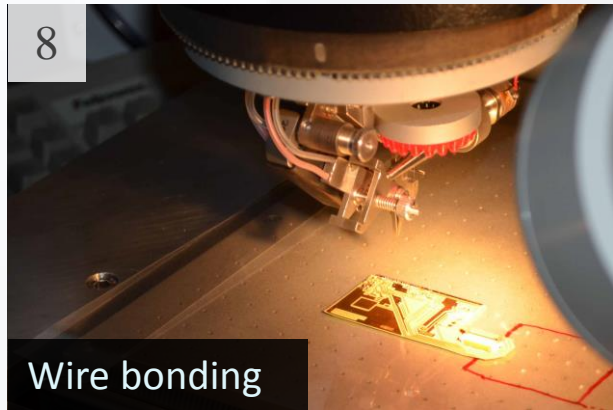
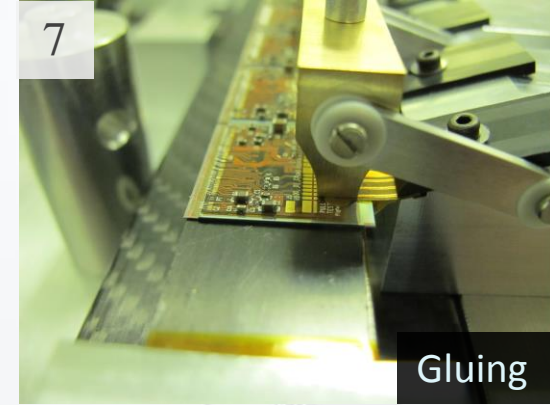
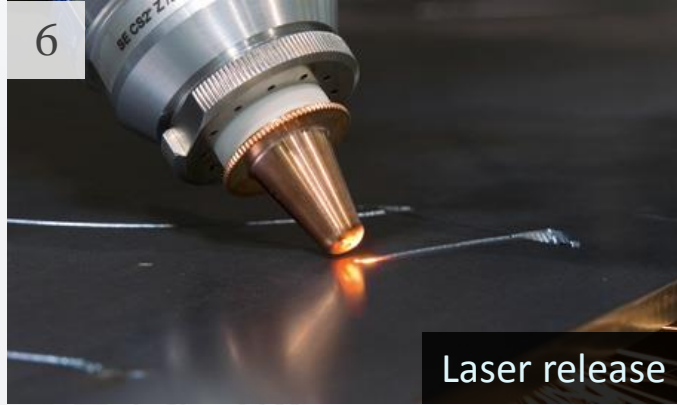
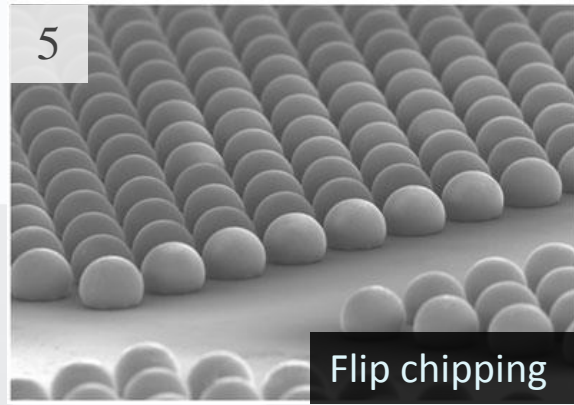
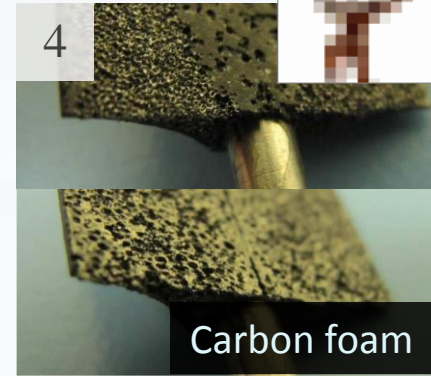
Carbon stave

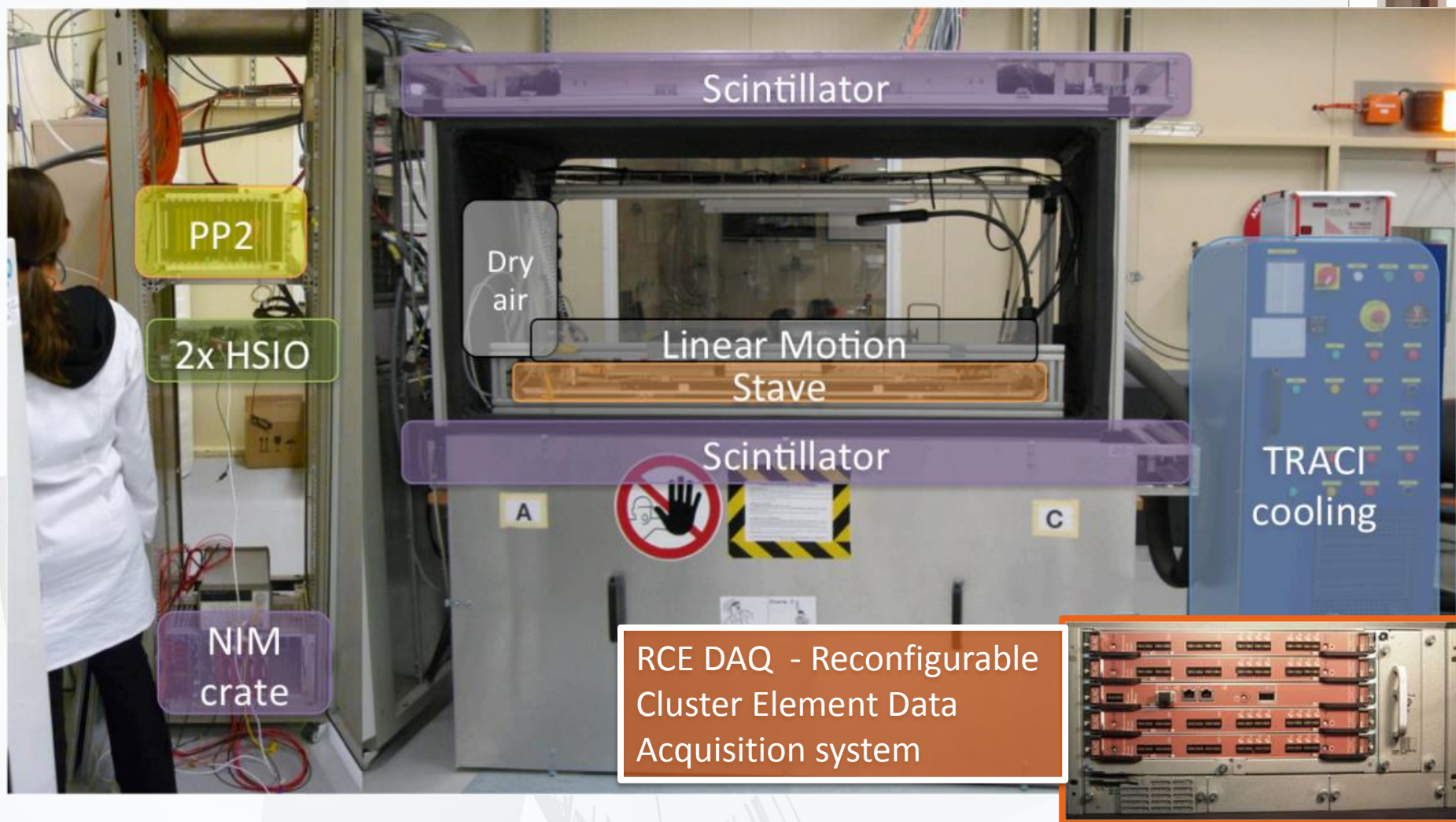


(Here's one we made earlier)



Stave flexes

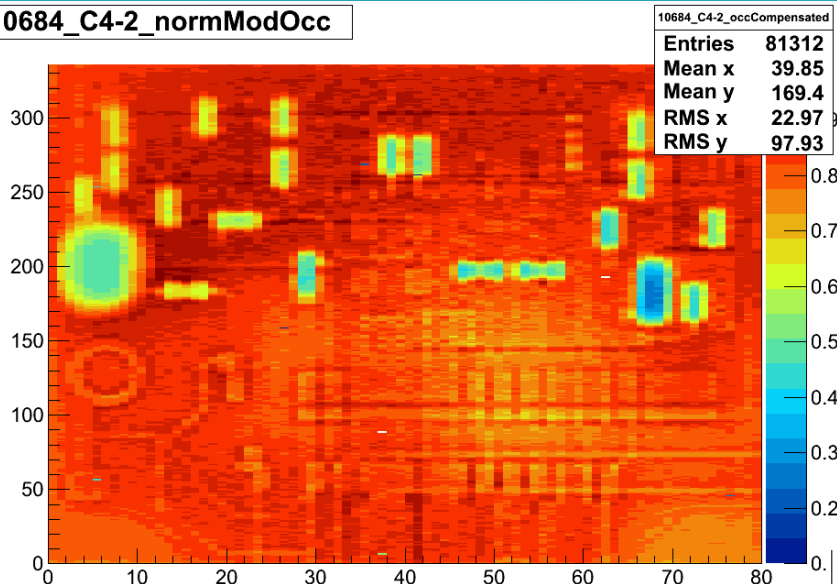




SR1 – IBL StaveTest setup. Note the linear motor above the stave, that moves sources over the modules for self-trigger tests. Signals are passed from the test area to the DAQ in the racks.



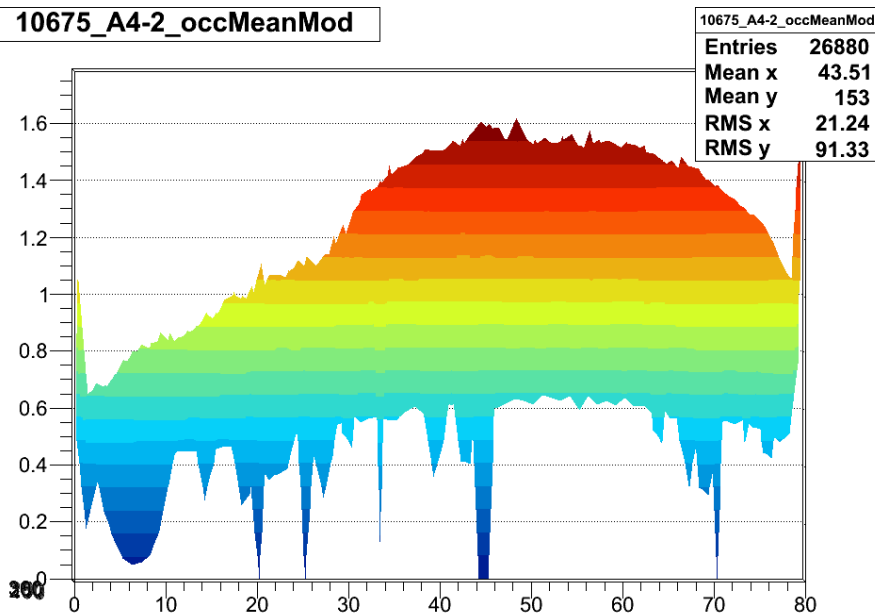
10684_C4-2_normModOcc



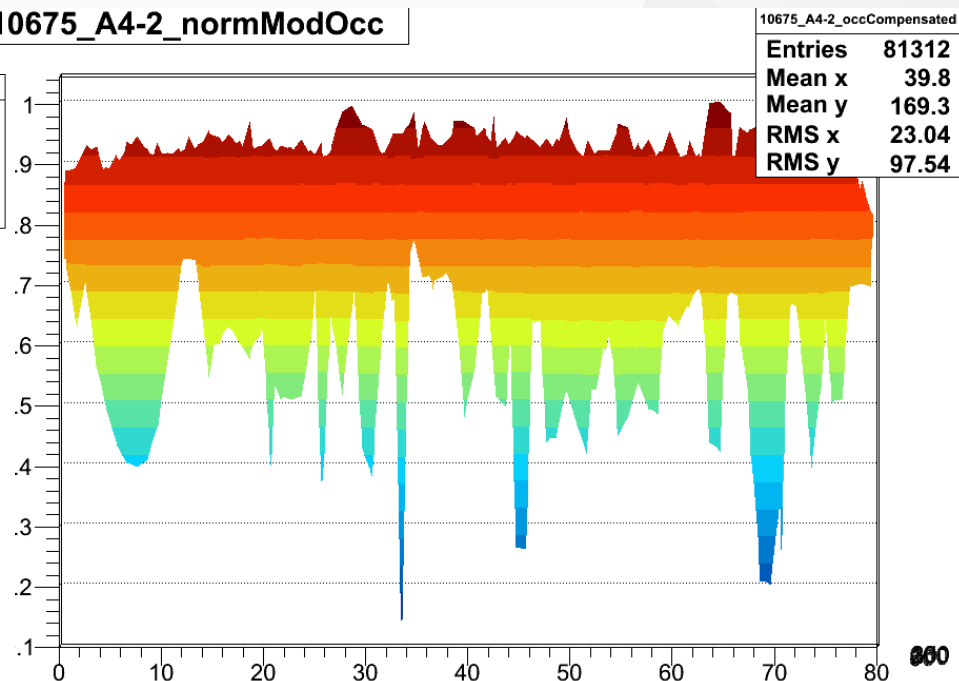
Self-triggered source scans have a heightened occupancy where the source is directly above the chip.
 This makes features, such as areas of low collection efficiency, difficult to pick out.

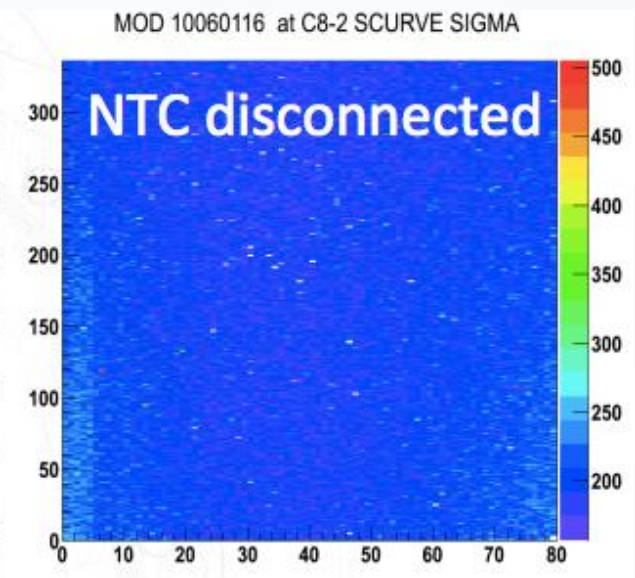
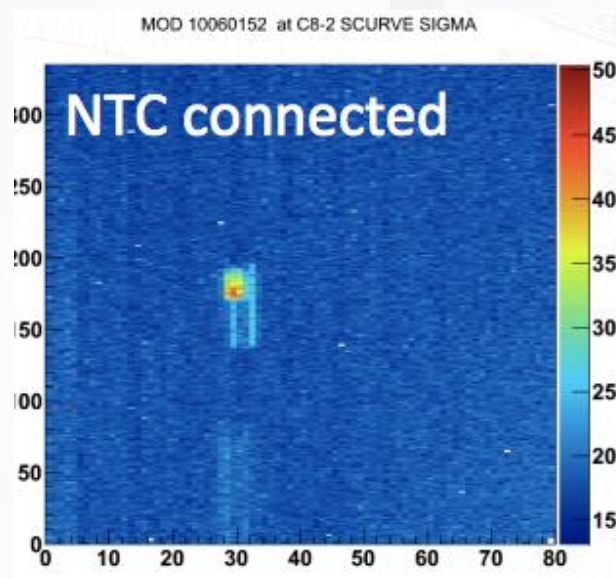
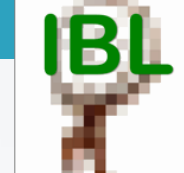
$$\text{occupancy} = \frac{\text{source rate}}{4\pi D_T^2} \times 0.05 \times 0.25$$

10675_A4-2_occMeanMod

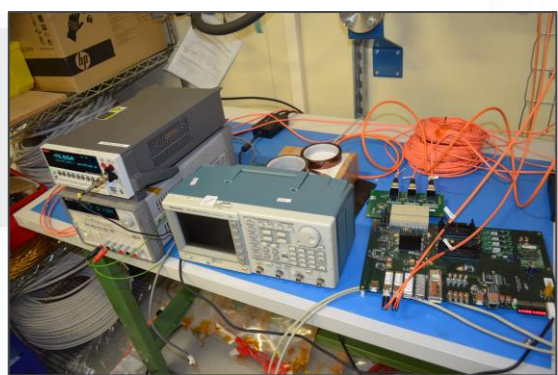


10675_A4-2_normModOcc

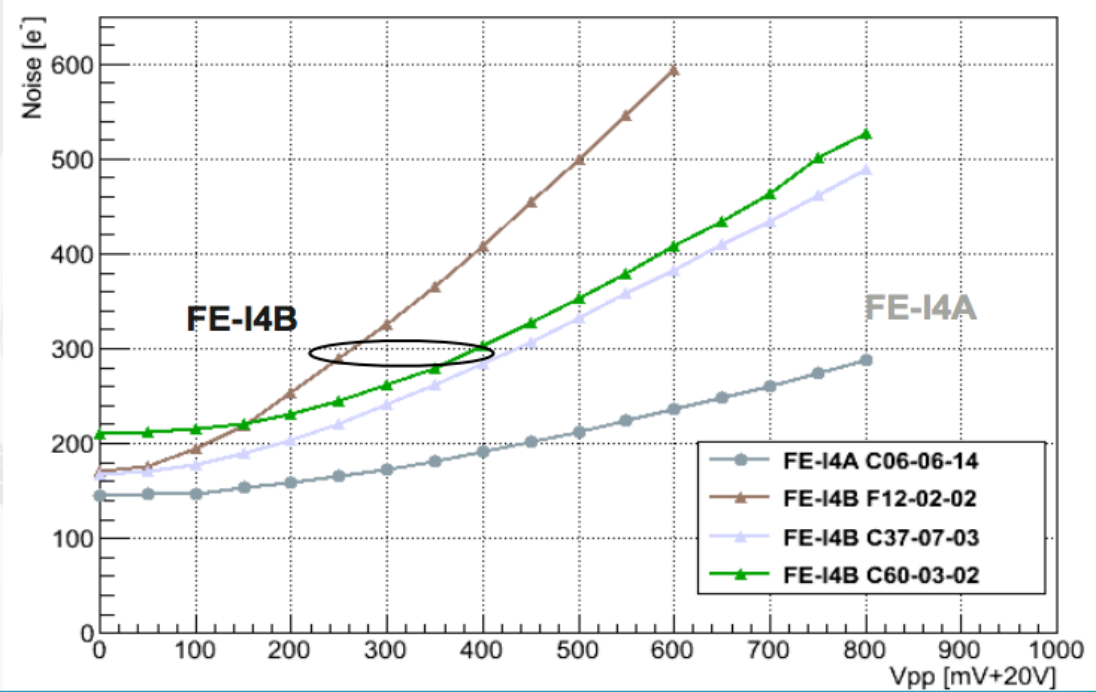




The NTC (negative temperature coefficient resistor) for a few 3D modules appears to be delivering high noise to the sensor. The reason for this is unknown: is it somehow coupling to the sensor?



High noise is observed in the 3D sensor modules. This noise changes with injected noise on the HV bias and should be compensated for by RC filters.



We've flown through the motivation for IBL and its make-up.

I've spoken briefly about the RCE analysis platform that forms a crucial part of the IBL QA procedure and how one of my tasks was adapting the self-trigger analysis.

My last month at CERN will be spent investigating the unaccounted for noise caused by the NTC and the 3D sensor noise response.



Questions?





